

### Main product characteristics

$I_{F(AV)}$	30 A
$V_{RRM}$	100 V
$T_j$ (max)	150° C
$V_F$ (typ)	0.385 V

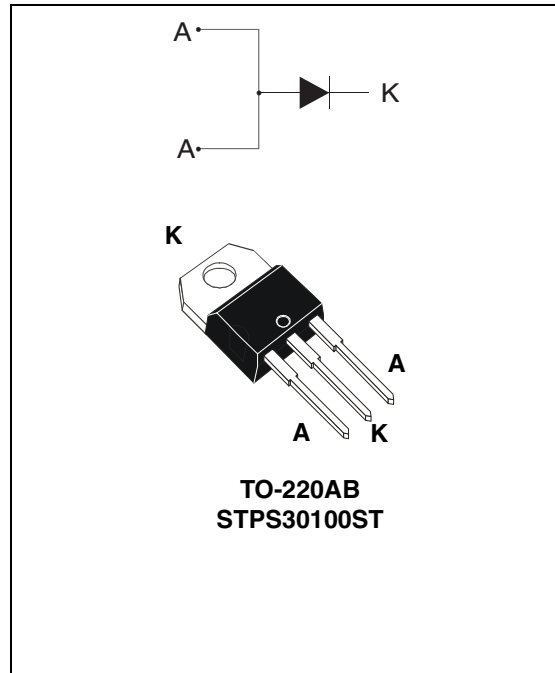
### Features and Benefits

- Avalanche rated
- Low  $V_F$
- Good trade off between leakage current and forward voltage drop
- High frequency operation
- Avalanche capability specified

### Description

Single Schottky rectifier, suited for high frequency switch mode power supply.

Packaged in TO-220AB, this device is intended to be used in notebook and game station adaptors, providing in these applications a good efficiency at both low and high load.



**Table 1. Absolute Ratings (limiting values)**

Symbol	Parameter		Value	Unit
$V_{RRM}$	Repetitive peak reverse voltage		100	V
$I_{F(RMS)}$	RMS forward current		60	A
$I_{F(AV)}$	Average forward current $\delta = 0.5$	$T_c = 125^\circ \text{C}$	30	A
$I_{FSM}$	Surge non repetitive forward current	$t_p = 10 \text{ ms sinusoidal}$	300	A
$P_{ARM}$	Repetitive peak avalanche power	$t_p = 1 \mu\text{s} \quad T_j = 25^\circ \text{C}$	26400	W
$T_{stg}$	Storage temperature range		-65 to + 175	°C
$T_j$	Maximum operating junction temperature <sup>(1)</sup>		150	°C

1.  $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th(j-a)}}$  condition to avoid thermal runaway for a diode on its own heatsink

# 1 Characteristics

**Table 2. Thermal resistance**

Symbol	Parameter	Value	Unit
$R_{th(j-c)}$	Junction to case	1	°C/W

**Table 3. Static electrical characteristics (per diode)**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit	
$I_R^{(1)}$	Reverse leakage current	$T_j = 25^\circ\text{C}$	$V_R = V_{RRM}$			175	$\mu\text{A}$
		$T_j = 125^\circ\text{C}$			20	50	mA
		$T_j = 25^\circ\text{C}$	$V_R = 70\text{ V}$			60	$\mu\text{A}$
		$T_j = 125^\circ\text{C}$			10	20	mA
$V_F^{(2)}$	Forward voltage drop	$T_j = 25^\circ\text{C}$	$I_F = 5\text{ A}$		0.475		V
		$T_j = 125^\circ\text{C}$			0.385		
		$T_j = 25^\circ\text{C}$	$I_F = 10\text{ A}$		0.555		
		$T_j = 125^\circ\text{C}$			0.475		
		$T_j = 25^\circ\text{C}$	$I_F = 15\text{ A}$		0.620	0.660	
		$T_j = 125^\circ\text{C}$			0.525	0.565	
		$T_j = 25^\circ\text{C}$	$I_F = 30\text{ A}$		0.740	0.800	
		$T_j = 125^\circ\text{C}$			0.605	0.655	

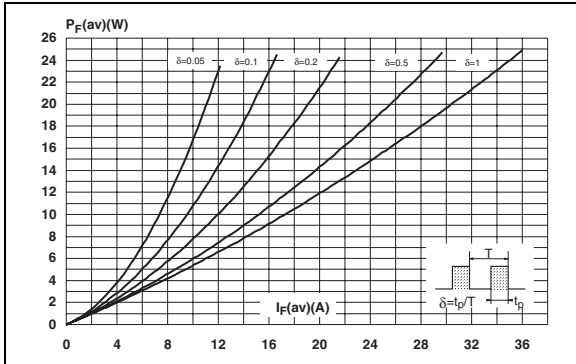
1. Pulse test:  $t_p = 5\text{ ms}$ ,  $\delta < 2\%$

2. Pulse test:  $t_p = 380\text{ }\mu\text{s}$ ,  $\delta < 2\%$

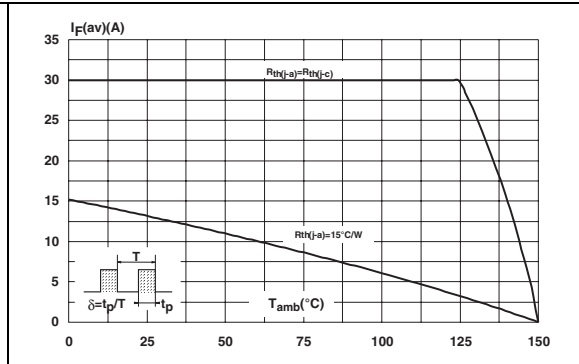
To evaluate the conduction losses use the following equation:

$$P = 0.475 \times I_{F(AV)} + 0.006 \times I_{F(RMS)}^2$$

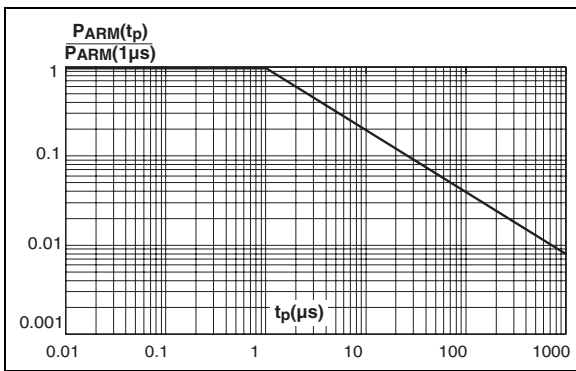
**Figure 1. Conduction losses versus average current**



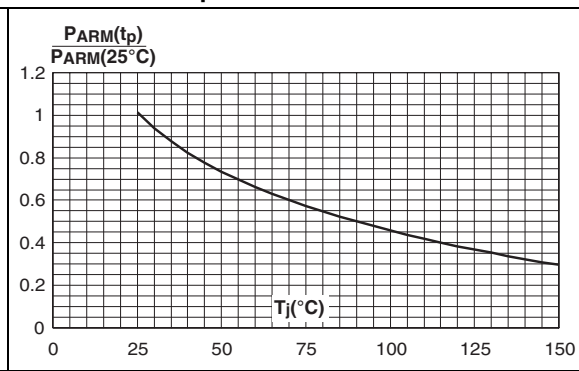
**Figure 2. Average forward current versus ambient temperature ( $\delta = 0.5$ )**



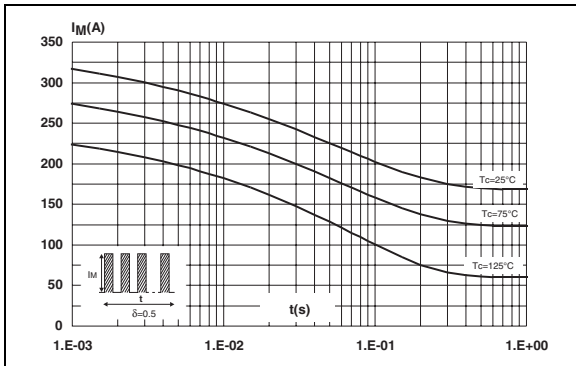
**Figure 3. Normalized avalanche power derating versus pulse duration**



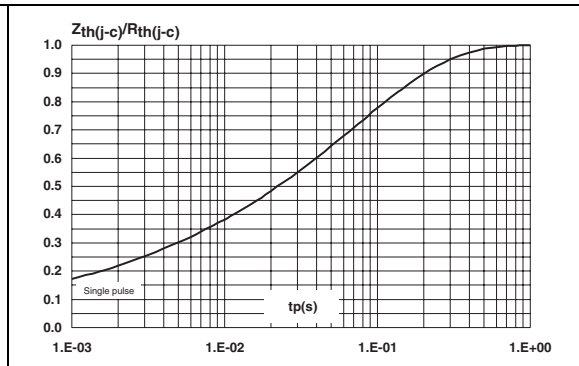
**Figure 4. Normalized avalanche power derating versus junction temperature**



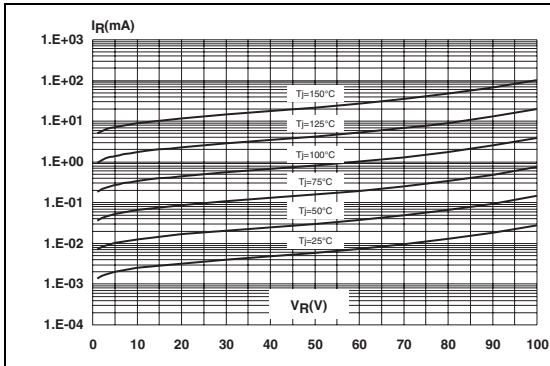
**Figure 5. Non repetitive surge peak forward current versus overload duration (maximum values)**



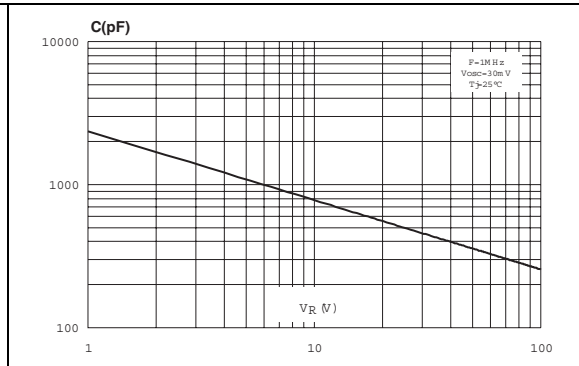
**Figure 6. Relative variation of thermal impedance junction to case versus pulse duration**



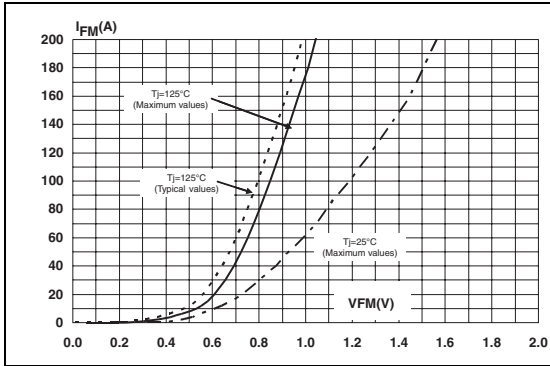
**Figure 7. Reverse leakage current versus reverse voltage applied (typical values)**



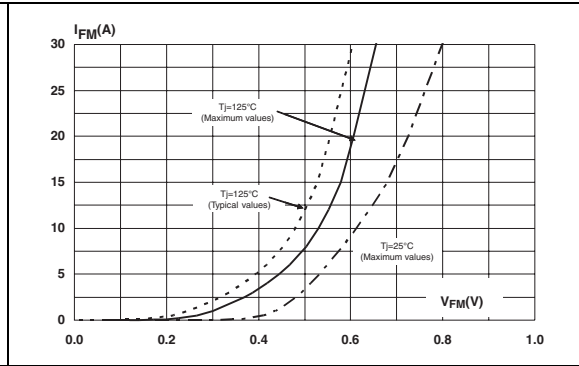
**Figure 8. Junction capacitance versus reverse voltage applied (typical values)**



**Figure 9. Forward voltage drop versus forward current (high level)**



**Figure 10. Forward voltage drop versus forward current (low level)**



## 2 Package Information

Epoxy meets UL94,V0

**Table 4. TO-220AB dimensions**

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	15.20		15.90	0.598		0.625
a1		3.75			0.147	
a2	13.00		14.00	0.511		0.551
B	10.00		10.40	0.393		0.409
b1	0.61		0.88	0.024		0.034
b2	1.23		1.32	0.048		0.051
C	4.40		4.60	0.173		0.181
c1	0.49		0.70	0.019		0.027
c2	2.40		2.72	0.094		0.107
e	2.40		2.70	0.094		0.106
F	6.20		6.60	0.244		0.259
ØI	3.75		3.85	0.147		0.151
I4	15.80	16.40	16.80	0.622	0.646	0.661
L	2.65		2.95	0.104		0.116
I2	1.14		1.70	0.044		0.066
I3	1.14		1.70	0.044		0.066
M		2.60			0.102	

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### 3 Ordering Information

Ordering type	Marking	Package	Weight	Base qty	Delivery mode
STPS30100ST	STPS30100ST	TO-220AB	2.23 g	50	Tube

### 4 Revision History

Date	Revision	Changes
24-Oct-2006	1	First issue

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